Notification Number: 20			2016	20160901002		Notification Date:		Sept. 13, 2016		
Title: Datasheet update for HD3SS214										
Customer Contact: PCN Manage			anager		Dept: Qu		Qua	Quality Services		
Change Type:										
Assembly Site				Design				Wafer Bump Site		
Assembly Process			\mathbb{X}	Data Sheet				Wafer Bump Material		
Assembly Materials				Part number change				Wafer Bump Process		
Mechanical Specification				Test Site				Wafer Fab Site		
Packing/Shipping/Labeling				Test Process				Wafer Fab Materials		
									Wafer Fab	Process

Notification Details

Description of Change:

Texas Instruments Incorporated is announcing an information only notification.

The product datasheet(s) is being updated as summarized below.

The following change history provides further details.

INSTRUMENTS	SLAS90	HD3SS214 SLAS907A – DECEMBER 2015–REVISED JULY 2016		
Changes from Original (December	2015) to Revision A	Page		
Changed DC2(p) to DC2(n) in Pi	n Functions			
Changed DC2(n) to DC2(p) in Pin Functions				
datasheet number will b	e changing.			
vice Family	Change From:	Change To:		
vice Family	Change From	enange ror		

These changes may be reviewed at the datasheet links provided. <u>http://www.ti.com/product/HD3SS214</u>

Reason for Change:					
To more accurately reflect device characteristics.					
Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):					
No anticipated impact. This is a specification change announcement only. There are no changes to the actual device.					
Changes to product identification resulting from this PCN:					
None.					
Product Affected:					
HD3SS214IZQER	HD3SS214ZQER				

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com